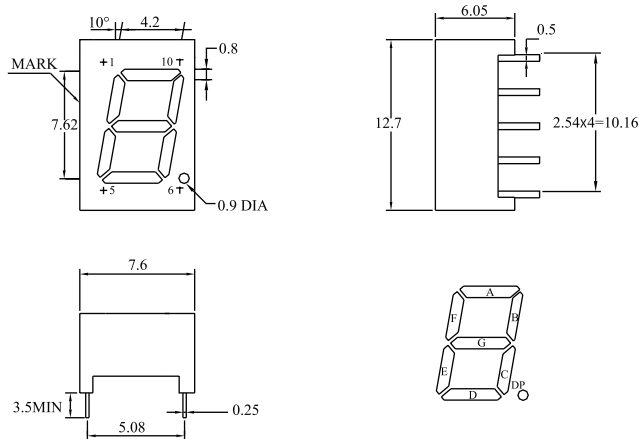


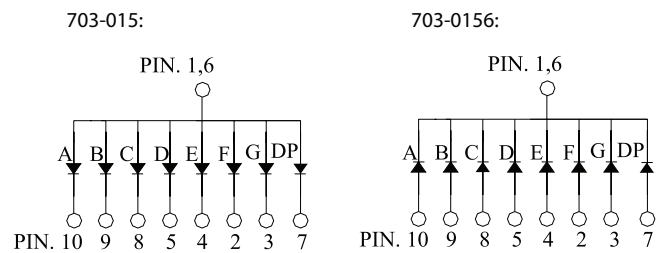
0.3" Single Digit Display



Package Dimensions:



Internal Circuit Diagram:



All dimensions are in mm
 Tolerance: ± 0.25 mm
 The slope angle of any PIN may be $\pm 5^\circ$ max

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Unit
Power Dissipation - Pre Segment	P _D	78	mW
Pulse Current (1/10 Duty Cycle, 0.1ms Pulse Width) - Per Chip	I _{FP}	100	mA
Forward Current - Per Chip	I _F	30	mA
Reverse (Leakage) Current - Per Chip	I _r	100	μA
Reverse Voltage - Per Chip	V _R	5	V
Operating Temperature Range	Topr.	-25 to +85	°C
Storage Temperature Range	Tstg.	-40 to +100	°C
Soldering Temperature	Tsol.	Dip Soldering: 260°C for 5sec. Hand Soldering: 350°C for 3 sec.	



Electrical & Optical Characteristics: Hyper Red

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity - Per Segment	I_v	$I_f=10\text{mA} / \text{seg}$	0.72	2.3		mcd
Forward Voltage	V_f	$I_f=20\text{mA} / \text{seg}$		2.1	2.6	V
Peak Wavelength	λ_p	$I_f=20\text{mA} / \text{seg}$		567		nm
Dominant Wavelength	λ_d	$I_f=20\text{mA} / \text{seg}$		572		nm
Reverse Current - Per Chip (Leakage Current - Per Chip)	I_r	$V_r=5\text{V}$			100	μA
Spectrum Line Halfwidth	$\Delta\lambda$	$I_f=20\text{mA} / \text{seg}$		30		deg
Response Time	T			250		nm

Note: Customer's special requirements are also welcome.

Typical Electrical & Optical Characteristics Curves:

(25°C Ambient temperature unless otherwise noted)

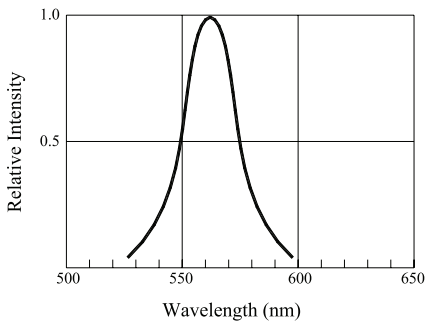


Fig.1 RELATIVE INTENSITY VS. WAVELENGTH

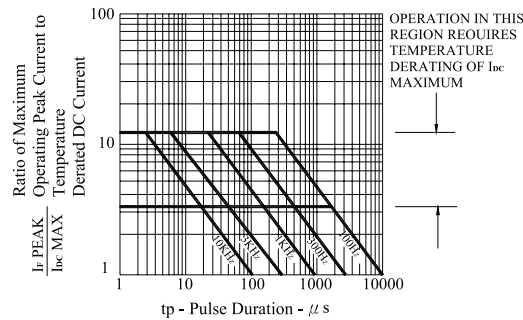


Fig.2 MAXIMUM TOLERABLE PEAK CURRENT VS. PULSE DURATION

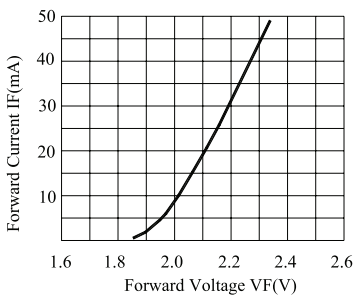


Fig.3 FORWARD CURRENT VS. FORWARD VOLTAGE PER CHIP

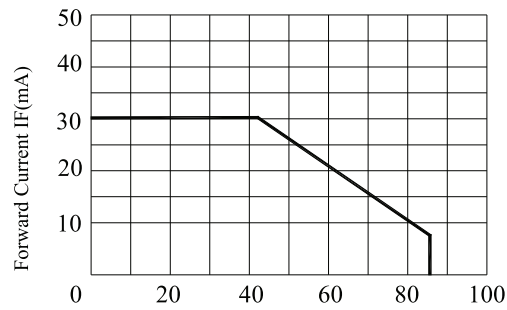


Fig.4 FORWARD CURRENT VS. DERATING CURVE

0.3" Single Digit Display

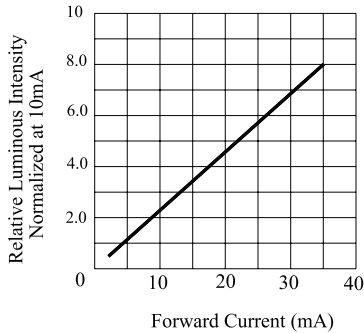


Fig.5 RELATIVE LUMINOUS INTENSITY VS. FORWARD CURRENT

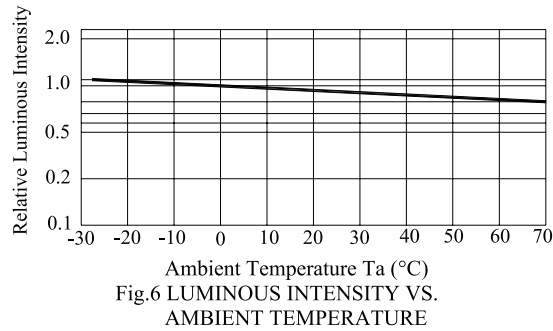


Fig.6 LUMINOUS INTENSITY VS. AMBIENT TEMPERATURE

Part Number Table

LED Chip		Face Colour		Part Number
Material	Emitting Colour	Surface	Segments	
GaP / GaP	Green	Grey	White	703-0155
GaP / GaP	Green	Grey	White	703-0156

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